

## REMARKS

This application has been reviewed in light of the Office Action dated August 11, 2006. Claims 1 – 6, 9, 10 and 11 are now presented for examination. Claims 12 – 16, 19 and 20 have been canceled. Claims 7, 8, 17 and 18 have been previously withdrawn. Claims 1 and 11 have been amended to more particularly point out and distinctly claim the subject matter regarded as the invention. Support for these amendments is detailed in the remarks that follow. No new matter has been added.

Claims 1 and 11 are independent.

Favorable review is respectfully requested.

### The §103 rejection:

Claims 1, 4, and 9 - 11 have been rejected by the Examiner under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. 2004-172489 Naoto.

Claims 1 and 11 have been amended, as suggested by the Examiner, to further clarify the original amendment. Accordingly, no new matter has been added. Specifically, claims 1 and 11 have been amended to more particularly claim that the lower power density device has a reduced thickness than the thickness of the higher power density device. Support for this amendment is found at least in paragraph [0023].

The present invention provides a structure and method where the lower power density devices are thinned to insure that after the devices are mounted on the substrate, the higher power density devices will project above the lower power density devices. As the Examiner acknowledges, this limitation is not disclosed in the reference. Naoto does not teach or disclose a lower power density device and a higher power density device where the lower power density device is thinned to be thinner than the higher power density device.

Applicants respectfully disagree that it would have been obvious to one of ordinary skill in the art, in view of Naoto, to provide a structure and method where the lower power density devices are thinned to insure that after the devices are mounted on the substrate, the higher power density devices will project above the lower power density devices. Naoto does not teach or suggest using devices of different thickness tailored to address heat management. Naoto is directed to creating more uniform heat dissipation for packages having chips of variable size and height. This is accomplished with hardware such as a curved

plate or cylindrical metal rings. There is no teaching or suggestion to thin the low power density devices to insure that after the devices are mounted on the substrate, the higher power density devices will project above the lower power density devices. Accordingly, claims 1 and 11, as amended, are not anticipated by the reference.

Since claims 4, 9 and 10 depend from claim 1, and since claim 1, as amended, is believed to be allowable, then claims 4 and 9 are believed to be allowable as well.

Claims 2, and 3 have been rejected by the Examiner under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. 2004-172489 Naoto, in view of Patel, U.S. Patent No. 6,850,411.

Since claims 2 and 3 depend from claim 1, and since claim 1, as amended, is believed to be allowable, then claims 2 and 3 are believed to be allowable as well.

Claim 5 has been rejected by the Examiner under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. 2004-172489 Naoto, in view of Daves, U.S. Patent No. 6,292,369.

Since claim 5 depends from claim 1, and since claim 1, as amended, is believed to be allowable, then claim 5 is believed to be allowable as well.

Claims 6 has been rejected by the Examiner under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. 2004-172489 Naoto, in view of Irvanti, U.S. Patent No. 5,098,609.

Since claim 6 depends from claim 1, and since claim 1, as amended, is believed to be allowable, then claim 6 is believed to be allowable as well.

Summary:

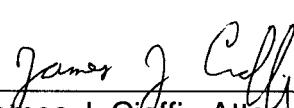
In view of all the preceding amendments and remarks, it is respectfully requested that any objections or rejections to this application be reconsidered and withdrawn. Further action with respect to the present application is earnestly solicited. If the Examiner finds this application is deficient in any respect, the Examiner is invited to contact the undersigned at the Examiner's earliest possible convenience.

If a fee is believed to be necessary, the Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 09-0458.

For the foregoing reasons, allowance of the claims is respectfully solicited.

Respectfully submitted,  
***Evan G Colgan, et al.***

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